COMPLIANT

HALOGEN FREE



N-Channel 40 V (D-S) MOSFET



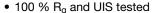
Top View

Bottom View

PRODUCT SUMMARY			
V _{DS} (V)	40		
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00047		
Q _g typ. (nC)	312		
I _D (A) ^a	795		
Configuration	Single		

FEATURES

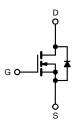
- TrenchFET® Gen V power MOSFET
- Leadership R_{DS(on)} minimizes power loss from conduction



- Standard level FET
- Enhance power dissipation and lower R_{thJC}
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Synchronous rectification
- Automation
- · OR-ing and hot swap switch
- Power supplies
- Motor drive control
- Battery management



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK® 10 x 12
Lead (Pb)-free and halogen-free	SiJK140E-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	40	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 175 °C)	T _C = 25 °C		795		
	T _C = 100 °C	I .	562		
	T _A = 25 °C	I _D	140 ^{b, c}		
	T _A = 100 °C		99 b, c	Α Α	
Pulsed drain current (t = 100 μs)		I _{DM}	900	^	
Continuous source-drain diode current	T _C = 25 °C		487		
	T _A = 25 °C	I _S	15 ^{b, c}		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	100		
Single pulse avalanche energy	L = 0.1 IIII	E _{AS}	500	mJ	
Maximum power dissipation	T _C = 25 °C		536		
	T _C = 100 °C		268	14/	
	T _A = 25 °C	P _D	17 ^{b, c}	W	
	T _A = 100 °C		8.3 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) c			260		

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum junction-to-ambient ^b	t ≤ 10 s	R_{thJA}	6.3	9	°C/W		
Maximum junction-to-case (drain)	Steady state	R_{thJC}	0.21	0.28	C/VV		

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK 10 x 12 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 39 °C/W



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SPECIFICATIONS ($T_J = 25 ^{\circ}\text{C}$, $t_J = 25 ^{\circ}\text{C}$)	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			1	1		<u> </u>	
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	40	-	_	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	22	-		
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	Б .		-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.4	-	3.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μА	
	IDSS	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10		
Drain-source on-state resistance a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.00034	0.00047	Ω	
Forward transconductance ^a	9fs	V _{DS} = 25 V, I _D = 100 A	-	450	-	S	
Dynamic ^b			•			•	
Input capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz	-	18 510	-	pF	
Output capacitance	C _{oss}		-	8540	-		
Reverse transfer capacitance	C _{rss}		-	555	-		
Total gate charge	Q_{g}		-	312	470	nC	
Gate-source charge	Q _{gs}	$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	84	-		
Gate-drain charge	Q _{gd}		-	70	-		
Output charge	Q _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	220	-		
Gate resistance	R_{g}	f = 1 MHz	0.22	1.1	2.2	Ω	
Turn-on delay time	t _{d(on)}		-	40	80		
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_1 = 4 \Omega, I_D \cong 10 \text{ A},$	-	45	90	1	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	85	170	ns	
Fall time	t _f		-	45	90]	
Drain-Source Body Diode Characteristi	cs		•			•	
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	487		
Pulse diode forward current	I _{SM}		-	-	900	_ A	
Body diode voltage	V _{SD}	$I_S = 10 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.7	1.1	V	
Body diode reverse recovery time	t _{rr}		-	105	210	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	310	620	nC	
Reverse recovery fall time	t _a	T _J = 25 °C	-	64	-		
Reverse recovery rise time	t _b		-	41	-	ns	

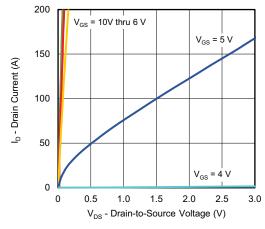
Notes

- a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

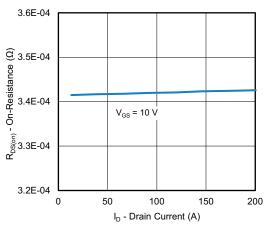
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



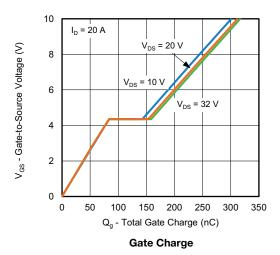
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

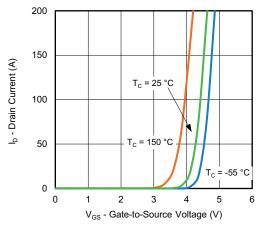


Output Characteristics

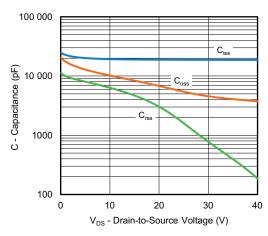


On-Resistance vs. Drain Current and Gate Voltage

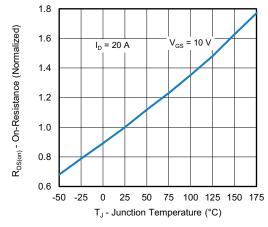




Transfer Characteristics



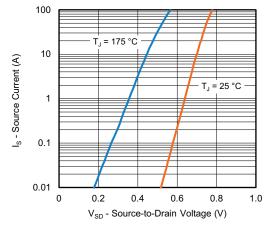
Capacitance



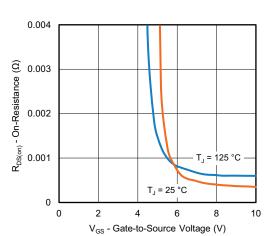
On-Resistance vs. Junction Temperature



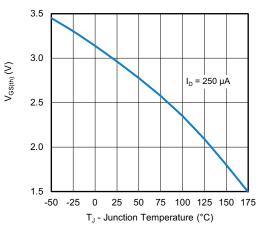
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



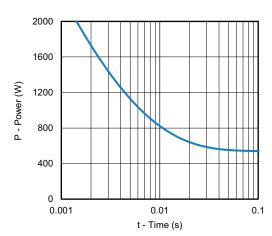
Source-Drain Diode Forward Voltage



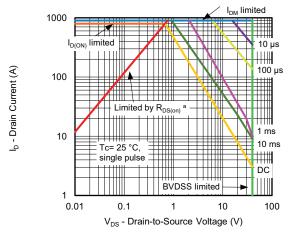
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Case



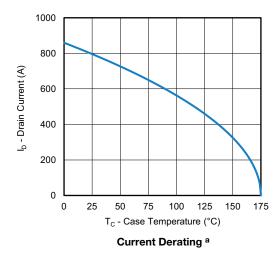
Safe Operating Area, Junction-to-Ambient

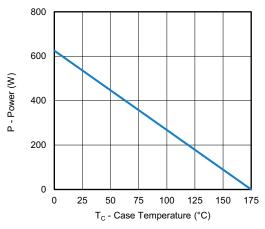
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

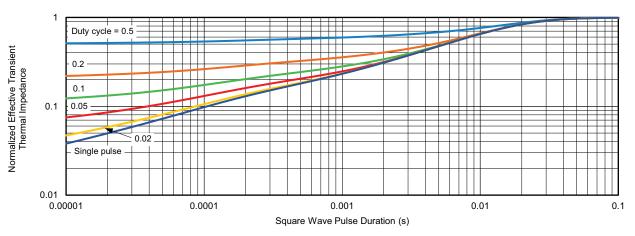


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Power, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Case

Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

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